

# Ultrafast Diode 60 A, 400 V

# FFH60UP40S, FFH60UP40S3

#### **Description**

The FFH60UP40S, FFH60UP40S3 is an ultrafast diode with low forward voltage drop and rugged UIS capability. This device is intended for use as freewheeling and clamping diodes in a variety of switching power supplies and other power switching applications. It is specially suited for use in switching power supplies and industrial application as welder and UPS application.

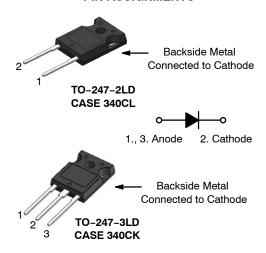
#### **Features**

- Ultrafast Recovery,  $T_{rr} = 85 \text{ ns}$  (@  $I_F = 60 \text{ A}$ )
- Max Forward Voltage,  $V_F = 1.3 \text{ V}$  (@  $T_C = 25^{\circ}\text{C}$ )
- Avalanche Energy Rated
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

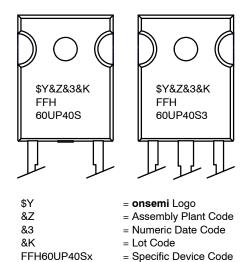
#### **Applications**

- General Purpose
- SMPS, Welder, UPS
- Free-wheeling Diode for Motor Application
- Power Switching Circuits

#### **PIN ASSIGNMENTS**



#### **MARKING DIAGRAM**



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

# FFH60UP40S, FFH60UP40S3

# **ABSOLUTE MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{RRM}$	Peak Repetitive Reverse Voltage	400	V
$V_{RWM}$	Working Peak Reverse Voltage	400	V
$V_{R}$	DC Blocking Voltage	400	V
I <sub>F(AV)</sub>	Average Rectified Forward Current @ T <sub>C</sub> = 139°C	60	Α
I <sub>FSM</sub>	Non-repetitive Peak Surge Current 60 Hz Single Half-Sine Wave	600	Α
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Maximum Thermal Resistance, Junction to Case	0.2	°C/W

#### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parar	neter	Min	Тур	Max	Unit
V <sub>F</sub> (Note 1)	I <sub>F</sub> = 60 A	T <sub>C</sub> = 25°C	-	1.06	1.3	V
		T <sub>C</sub> = 100°C	_	0.99	-	
I <sub>R</sub> (Note 1)	V <sub>R</sub> = 400 V	T <sub>C</sub> = 25°C	-	-	100	μΑ
		T <sub>C</sub> = 100°C	-	-	500	
t <sub>rr</sub>	$I_F = 60 \text{ A}, \text{ di}_F/\text{dt} = 200 \text{ A}/\mu\text{s}, \ V_B = 260 \text{ V}$	T <sub>C</sub> = 25°C	-	59	85	ns
	V <sub>R</sub> = 200 V	T <sub>C</sub> = 100°C	-	96	-	
$W_{AVL}$	Avalanche Energy (L = 40 mF	1)	50	_	-	mJ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **ORDERING INFORMATION**

Part Number	Device Marking	Package	Shipping
FFH60UP40S	FFH60UP40S	TO-247-2LD (Pb-Free / Halogen Free)	450 Units / Tube
FFH60UP40S3	FFH60UP40S3	TO-247-3LD (Pb-Free / Halogen Free)	450 Units / Tube

<sup>1.</sup> Pulse: Test Pulse Width = 300 μs, Duty Cycle = 2%

# FFH60UP40S, FFH60UP40S3

# **TEST CIRCUIT AND WAVEFORM**

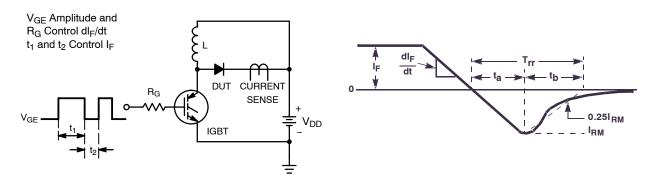


Figure 1. Diode Reverse Recovery Test Circuit and Waveform

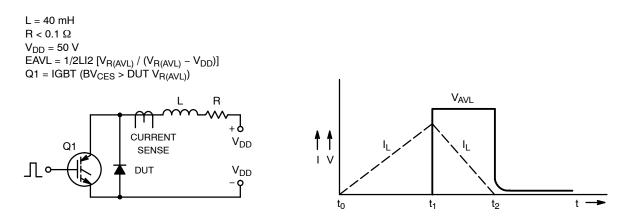


Figure 2. Unclamped Inductive Switching Test Circuit & Waveform

# FFH60UP40S, FFH60UP40S3

#### TYPICAL PERFORMANCE CHARACTERISTICS

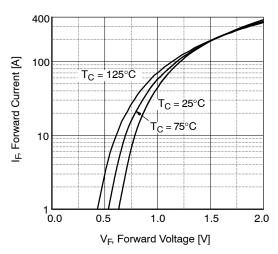


Figure 3. Typical Forward Voltage Drop vs. Forward Current

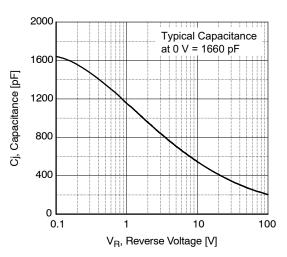


Figure 5. Typical Junction Capacitance

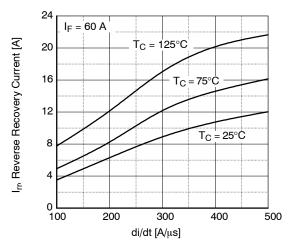


Figure 7. Typical Reverse Recovery Current vs. di/dt

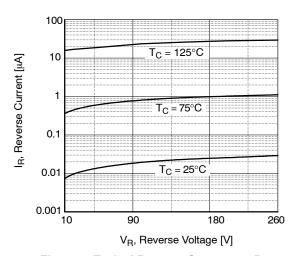


Figure 4. Typical Reverse Current vs. Reverse Voltage

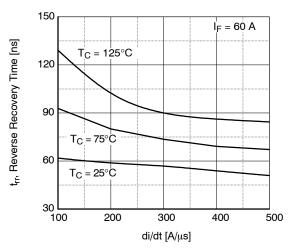


Figure 6. Typical Reverse Recovery Time vs. di/dt

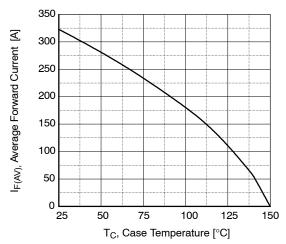
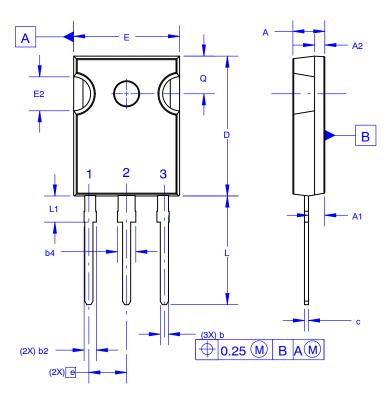


Figure 8. Forward Current Derating Curve

#### TO-247-3LD SHORT LEAD

CASE 340CK ISSUE A





- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

# GENERIC MARKING DIAGRAM\*



XXXX = Specific Device Code

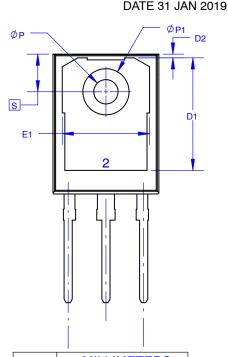
A = Assembly Location

Y = Year

WW = Work Week

ZZ = Assembly Lot Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



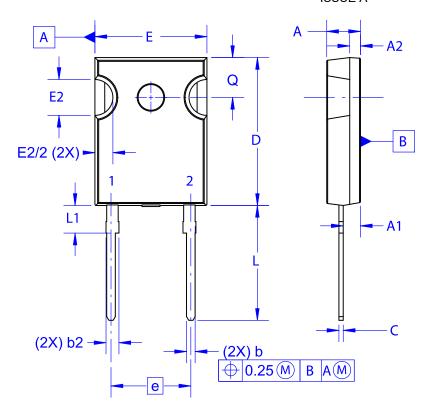
DIM	MIL	LIMET	LIMETERS		
DIIVI	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A1	2.20	2.40	2.60		
<b>A2</b>	1.40	1.50	1.60		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D	20.32	20.57	20.82		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E	15.37	15.62	15.87		
E1	12.81	?	~		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	15.75	16.00	16.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Ø <b>P1</b>	6.60	6.80	7.00		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		

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**DATE 03 DEC 2019** 

#### TO-247-2LD CASE 340CL **ISSUE A**





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#### **GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code

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	D, 11 E 00 E	LC 2010
Ø P —		Ø P1 D2
S E1 —		D1

DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
A1	2.29	2.40	2.66	
A2	1.30	1.50	1.70	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
С	0.51	0.61	0.71	
D	20.32	20.57	20.82	
D1	16.37	16.57	16.77	
D2	0.51	0.93	1.35	
Е	15.37	15.62	15.87	
E1	12.81	~	~	
E2	4.96	5.08	5.20	
е	~	11.12	~	
L	15.75	16.00	16.25	
L1	3.69	3.81	3.93	
ØΡ	3.51	3.58	3.65	
Ø <b>P</b> 1	6.61	6.73	6.85	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	

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